AMC to PCIe Adaptor Schematic

SCHEMATIC PAGE DESCRIPTION :

01 : COVER SHEET
02 : BLOCK DIAGRAM
03 : INTERFACES
04 : REVISION HISTORY & DUMMY PARTS

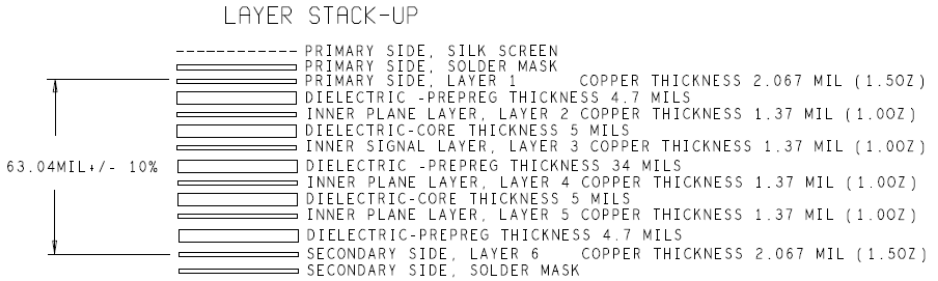
MAJOR REVISION HISTORY :

PCB REV.	SCH. REV.	DESCRIPTION	DATE
1.0	1.0	Proto Build	31-March-2011
2.0	2.1	Release For Production of Rev A	20-May-2011
3.1	3.1	Release For Production of Rev B	21-July-2011

PCB Mechanical Details :

1. PCB SIZE: 9.44" x 3.92"
2. PCB MATERIAL: FR408
3. NUMBER OF LAYERS: 06
4. IMPEDANCE CONTROL: YES

PCB LAYER STACK-UP DETAILS :



NOTES, UNLESS OTHERWISE SPECIFIED :

1. RESISTANCE VALUES ARE IN OHMS.
2. CAPACITANCE VALUES ARE IN MICROFARADS.
3. PARTS NOT INSTALLED ARE INDICATED WITH 'NU'.
4. SIGNAL NET NAMES WITH "#" SUFFIX, ARE ACTIVE LOW SIGNALS.

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Title: COVER SHEET		
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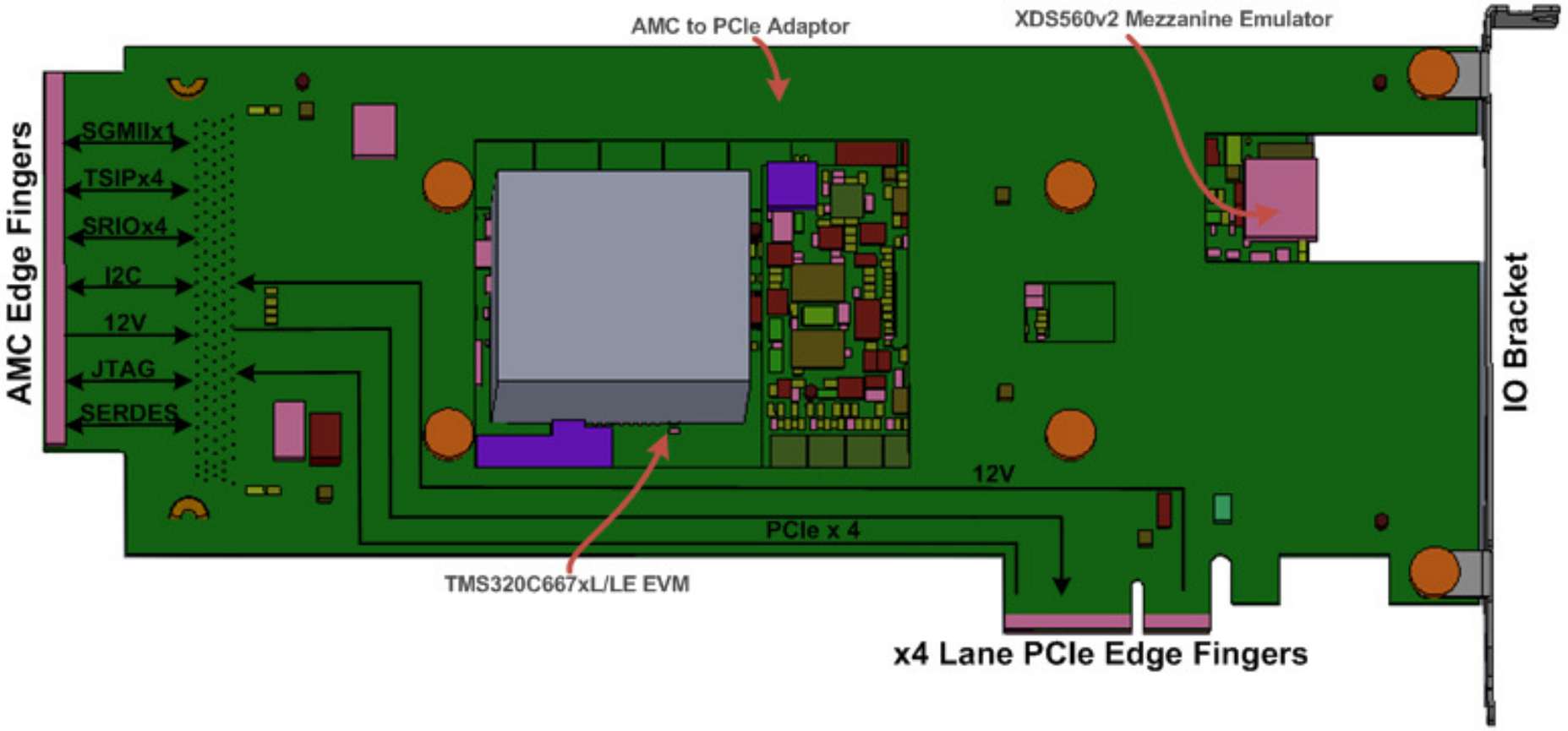
BLOCK DIAGRAM



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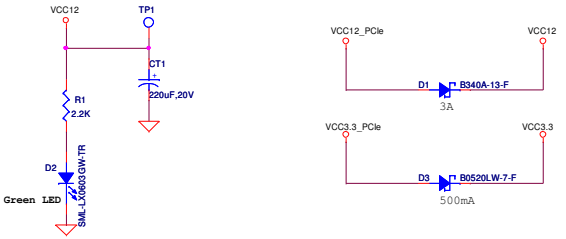
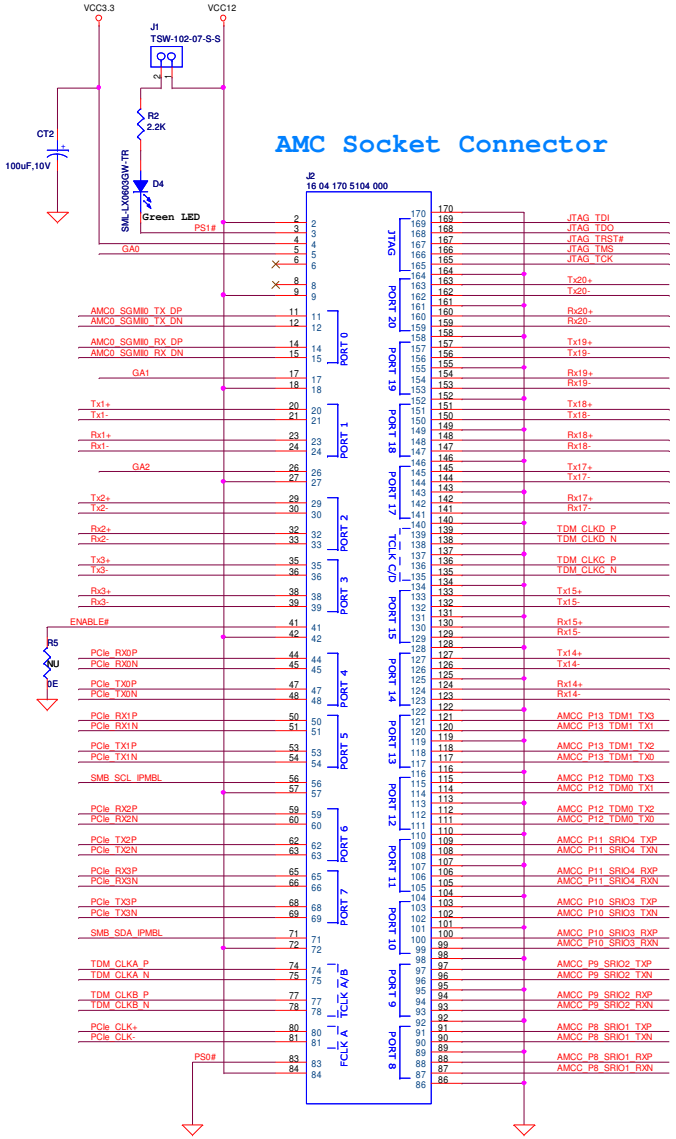
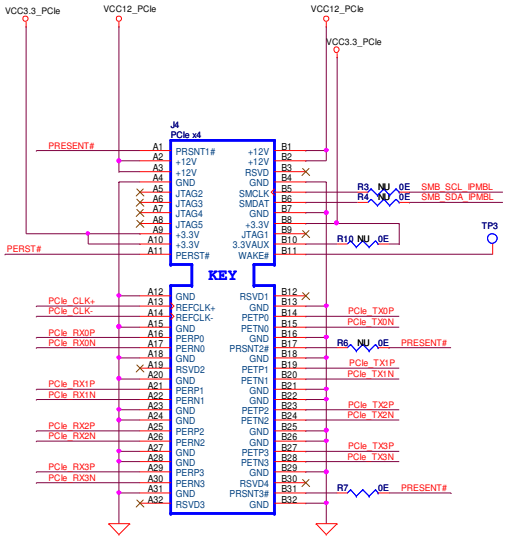
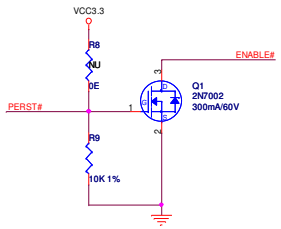


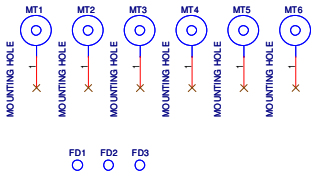






NOTE:
When PERST# = 0; Q1 = OFF; MMC in Reset
When PERST# = 1; Q1 = ON; MMC out of Reset

MMC (MSP430) in C6678 EVM shall assert POR (MMC_POR_IN_AMC#) each time it is out of Reset.



Project: AMC to PCIe Adaptor		Designed for TI by eInfochips
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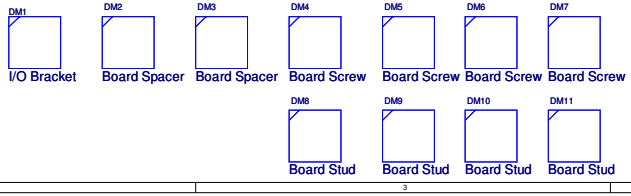
REVISION HISTORY

PCB REV.	SCH. REV.	CHANGE DESCRIPTION	DATE	AUTHOR
1.0	0.1	Initial Draft	March 05, 2011	eInfochips
	0.2	R2 and R4 are removed, now single net of VCC12.	March 25, 2011	eInfochips
	0.3	Two Power diodes D3 and D4 are added on PCIe powers. Shunt-post J4 added. Extra cap CT3 removed. AMC Ports 1,2,3,14,17,18,19,20 and JTAG from socket connector connected with AMC edge fingers. I2C bus of PCIe is connected to IPMB bus of AMC Port 15 used as SERDES port	March 30, 2011	eInfochips
	Issue 1.0	Released for PCB Fabrication	March 31, 2011	eInfochips
2.0	2.0	Connection provision added for J4.B17 to connect with PRESENT# net AMC ENABLE# connected to PERST# through Open Drain Inverter	May 16, 2011	eInfochips
	2.1	0E Resistor connected on Pin J4.B31 (PRESNT3#)	May 20, 2011	eInfochips
	Issue 2.1	Released for Rev A PCB Fabrication	May 21, 2011	eInfochips
3.1	Issue 3.1	Layer stack-up changed from 4 layer to 6 layer. Dielectric material changed from FR4 to ISOLA FR408HR. VCC3.3 AUX isolated from VCC3.3 power plane using 0E resistor. Released for Rev B PCB Fabrication.	July 21, 2011	eInfochips

DUMMY COMPONENTS



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